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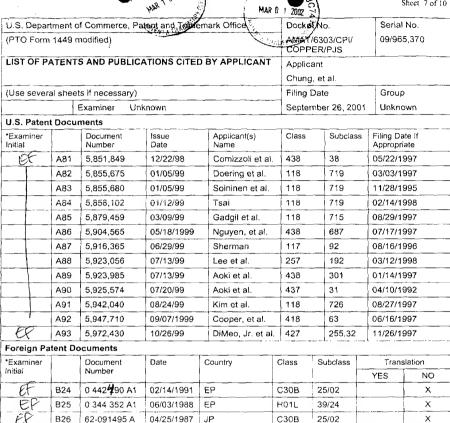
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PK.	A28	5,225,366	07/06/93	Yoder	437	108	06/22/1	990
1	A29	5,246,536	09/21/93	Nishizawa et al	156	610	03/10/1	989
	A30	5,250,148	10/05/93	Nishizawa et al.	156	611	11/12/1	991
	A31	5,254,207	10/19/93	Nishizawa et al.	156	601	11/30/1	992
	A32	5,256,244	10/26/93	Ackerman	156	613	02/10/1	992
	A33	5,270,247	12/14/93	Sakuma et al.	437	133	07/08/1	992
	A34	5,278,435	01/11/94	Van Hove et al.	257	184	06/08/1	992
	A35	5,281,274	01/25/94	Yoder	118	697	02/04/1	993
	A36	5,290,748	03/01/94	Knuuttila et al.	502	228	07/16/1	992
	A37	5,294,286	03/15/94	Nishizawa et al.	156	610	01/12/1	993
	A38	5,296,403	03/22/94	Nishizawa et al.	437	133	10/23/1	992
	A39	5,300,186	04/05/94	Kitahara et al.	156	613	04/07/1	992
EP	A40	5,311,055	05/10/94	Goodman et al.	257	593	11/22/1	991
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EF	B10	00/79576 A1	12/28/2000	wo	H01L	21/205		×
EF	B11	00/79019 A1	12/28/2000	wo	C23C	16/00		X
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ef	C5			lled deposition of Si ci., Vol. 82/83 (1994)			3binary re	action
Q	C6	Wise, et al., "Diet	hyldiethoxysilane	as a new precursor f	or SiO ₂ g	rowth on silico	n", Mat. Res	Soc.

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EF	A14	4,859,627	08/22/89	Sunakawa	437	81	07/01/19	886
	A15	4,861,417	08/29/89	Mochizuki et	al. 156	610	03/24/19	988
	A16	4,876,218	10/24/89	Pessa et al.	437	107	09/26/19	988
	A17	4,927,670	05/22/19	90 Erbil	427	255.3	06/22/19	988
	A18	4,931,132	06/05/90	Aspnes et al.	156	601	10/07/19	988
	A19	4,960,720	10/02/90	Shímbo	437	105	08/24/19	987
	A20	4,975,252	12/04/90	Nishizawa et	al. 422	245	05/26/19	989
	A21	4,993,357	02/19/91	Scholz	118	715	12/21/19	989
	A22	5,013,683	05/07/91	Petroff et al.	437	110	01/23/19	989
	A23	5,082,798	01/21/92	Arimoto	437	108	09/27/19	990
	A24	5,085,885	02/04/92	Foley et al.	477	38	09/10/19	990
	A25	5,091,320	02/25/92	Aspnes et al.	437	8	06/15/19	990
	A26	5,130,269	07/14/92	Kitahara et al	. 437	111	04/25/19	989
CE	A27	5,166,092	11/24/92	Mochizuki et	al. 437	105	10/30/19	990
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EF.	B6	01/29280 A1	04/26/200		C23C	16/32		X
	B7	01/27347 A1	04/19/200	1 WO	C23C	16/44		X
	B8	01/27346 A1	04/19/200	1 WO	C23C	16/44		X
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EP	A1	4,058,430	11/15/77	Suntola et al.	156	611	11/25/1	975
	A2	4,389,973	06/28/83	Suntola et al.	118	725	12/11/1	981
	А3	4,413,022	11/01/83	Suntola et al.	427	255.2	06/21/1	979
	A4	4,486,487	12/04/84	Skarp	428	216	04/25/1	983
	A5	4,767,494	08/30/88	Kobayashi et al	. 156	606	09/19/1	986
	A6	4,806,321	02/21/89	Nishizawa et al	422	245	07/21/1	985
	A7	4,829,022	05/09/89	Kobayashi et al	. 437	107	12/09/1	986
	8A	4,834,831	05/30/89	Nishizawa et al	. 156	611	09/04/1	987
	A9	4,838,983	06/13/89	Schumaker et al.	156	613	03/18/1	988
	A10	4,838,993	06/13/89	Aoki et al.	156	643	12/03/1	987
	A11	4,840,921	06/20/89	Matsumoto	437	89	06/30/1	988
	A12	4,845,049	07/04/89	Sunakawa	437	81	03/28/1	988
K	A13	4,859,625	08/22/89	Nishizawa et al	437	81	11/20/1	987
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	В3	01/36702 A1	05/25/2001	wo	C23C	16/00		Х
68	В4	01/29893 A1	04/26/2001	wo	H01L	21/768	_	Х
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			Chung, et al.	Unknown			
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	C17	NERAC Search - Atomic Layer Deposition, sear	ch dated October 16, 200)1			
	C18	Bader, et al., "Integrated Processing Equipment" 33, No. 5 (May 1, 1990), pp. 149-154	, Solid State Technology,	Cowan Pub., Vol.			
	C19	Choi, et al., "The effect of annealing on resistivity titanium diboride", J. Appl. Phys. 69(11) (June 1,	of low pressure chemica 1991), pp. 7853-7861	I vapor depositied			
ļ	C20	Choi, et al., "Stability of TiB_2 as a Diffusion Barrier on Silicon", J. Electrochem. Soc. 138(10) (October 1991), pp. 3062-3067					
H :	C21	"Cluster Tools for Fabrication of Advanced device Abstracts, 22" Conference Solid State Devices XP000178141	es" Jap. J. of Applied Phy and Materials (1990), pp.	rsics, Extended 849 – 852			
	C22	"Applications of Integrated processing", Solid Sta No. 12 (December 1, 1994), pp. 45-47	te Technology, US, Cowa	an Pub., Vol 37,			
3	C23	Kitigawa, et al., "Hydrogen-mediated low temper chemical vapor deposition", Applied Surface Scientific Control of the Control	ature epitaxy of Si in plassence (2000), pp. 30-34	ma-enhanced			
El	C24	Lee, et al., "Pulsed nucleation for ultra-high aspe Inc. (2001), pp. 1-2 (COPY NOT AVAILABLE TO	ct ratio tungsten plugfill", APPLICANT AT THIS TI	Novellus Systems			
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		C3	Suzuki, et al., "A 0.2-µm resistivity", IEDM 92-979		C-hydrazine-reduced TiN fi	Im with low
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		C5	IBM Tech. Disc. Bull. "Kr Control, (June 1990), pp		mic Scheduler in Distribute	ed Computer
		C6	IBM Tech. Disc. Bull. "Mi Advanced via Inspection		itasking Architecture for Top. 190-191	ool Control of the
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2 3 20	-	C8	Solanki, et al., "Atomic L State Letters, 3(10) (200		oper Seed Layers", Electron	chemical and Solid
APR.	<u>ර</u>	C9	NERAC.COM Retro Sea	rch: Atomic Layer Der	position of Copper, dated C	October 11, 2001
4		C10	NERAC.COM Retro Sea dated October 2, 2001	rch: Atomic Layer Dep	position / Epitaxy Aluminum	ı Oxide Plasma,
		C11	NERAC Search abstract Barriers", by Rossnagel,		osition of Ta and Ti for Inter ech., 18(4) (July 2000)	rconnect Diffusion
	1	C12	Abstracts of articles re at	omic layer deposition		
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1 -	B147	2001-240972	09/04/2001	JP	C23C	16/458			
	B148	2001-254181	09/18/2001	JP	C23C	16/46		\boxtimes	
	B149	2001-284042	10/12/2001	JP	H05B	33/04		X	
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	B154	01/15220	03/01/2001	wo	H01L	21/768			
	B155	00/11721	03/02/2000	wo	H01L	29/43			
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	B130	2000-031387	01/28/2000	JP	H01L	27/04	\boxtimes	
	B131	2000-058777	02/25/2000	JP	H01L	27/108		
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_ }	B50	02-106822	04/18/1990	JP	H01B	13/00		LE	
	B51	02-129913	05/18/1990	JP	H01L	21/205			
	B52	02-162717	06/22/1990	JP	H01L	21/20	\boxtimes		
	B53	02-172895	07/04/1990	JP	C30B	29/36			
	B54	02-196092	08/02/1990	JP	C30B	25/14	\square		
	B55	02-203517	08/13/1990	JP	H01L	21/205			
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	B57	02-230722	09/13/1990	JP	H01L	21/205			
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E S	B60	02-283084	11/20/1990	JP	H01S	3/18			
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A 60	B63	03-022569	01/30/1991	JP	H01L	29/804	<u> </u>		
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	B72	04-031391	02/03/1992	JP	C30B	23/08	-). <u>i</u>	. L	
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		B29	01-117017	05/09/	1989	JP	H01L	21/203		
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		B33	01-236657	09/21/	1989	JP	H01L	29/80		
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<u> </u>		B35	01-264218	10/20/	1989	JP	H01L	21/205	Ø	
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^{*}EXAMINER Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through tation if not in conformance and in a considered. Include copy of this form with your communication to applicant.

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^{*}EXAMINER*Initial if reference considered, whether or not citation is in conformance with MPEP 609: Draw line through station if not in conformance and not considered. Include copy of this form Aith your communication to applicant

U.S. Depa	tment c	of Commerce, Pater	ark Office	Docket No.		Serial No.	
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